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# Datasheet

### AS1360 1.5µA Low-Power, Positive Voltage Regulator

# **1** General Description

The AS1360 low-power, positive voltage regulator was designed to deliver up to 250mA while consuming only  $1.5\mu$ A of quiescent current. The device is available in fixed output voltages of 1.8, 2.1, 2.5, 3.0, 3.3, 4.0, 4.5 and 5.0V.

The device features integrated short-circuit and overcurrent protection.

The wide input voltage range, low-dropout voltage, and high-accuracy output voltage makes the device perfectly suited for 2- and 3- cell battery-powered and portable applications.

The low dropout voltage (650mV) prolongs battery life and allows high current in small applications when operated with minimum input-to-output voltage differentials.

The device features very stable output voltage (using only 1µF tantalum or aluminum-electrolytic capacitors), strict output voltage regulation tolerances ( $\pm 0.5\%$ ), and excellent line-regulation.

The AS1360 is available in a 3-pin SOT23 package.

### 2 Key Features

- Low Quiescent Current: 1.5µA
- Input Voltage Range: Up to 20V
- Low Dropout Voltage
- 250mV @ 100mA
- 400mV @ 200mA
- Fixed Output Voltages: 1.8, 2.1, 2.5, 3.0, 3.3, 4.0, 4.5, 5.0V
- High Output Current: 250mA (VOUT = 5.0V)
- High-Accuracy Output Voltage: ±1.5%
- Exceptional Line Regulation: 0.1%/V
- Low Temperature Drift: ±100ppm/°C
- Integrated Short-Circuit and Overcurrent Protection
- 3-pin SOT23 Package

# 3 Applications

The device is ideal for mobile phones, PDAs, digital cameras, smart battery packs, battery-powered alarms, solar-powered instruments, intelligent instruments, CO2 and smoke detectors, CPU power supplies, and any battery-powered application.

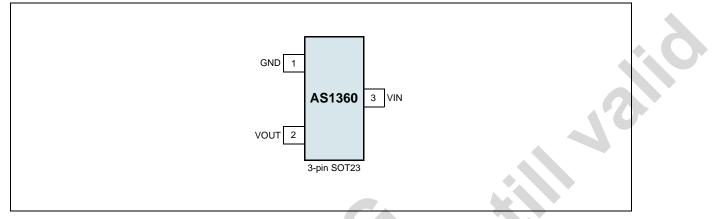
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Figure 1. AS1360 - Block Diagram

# 4 Pinout and Packaging

#### **Pin Assignments**

Figure 2. Pin Assignments (Top View)



#### **Pin Descriptions**

Table 1. Pin Descriptions

### 5 Absolute Maximum Ratings

Stresses beyond those listed in Table 2 may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in Section 6 Electrical Characteristics on page 4 is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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Iavie z.	Absolute	Ινιαλιπιμπ	naunys

Input Voltage         Input Voltage         Continuous Output Current         Peak Output Current         Output Voltage         Electrostatic Discharge         Electrostatic Discharge HBM         Thermal Information         Thermal Resistance $\Theta$ JA         Gemperature Ranges and Storage Condition         Storage Temperature Range         Package Body Temperature         Humidity non-condensing         Moisture Sensitive Level		+30 PD/ (VIN - VOUT) 500 VIN + 0.3V or +7V +/- 1 	V           mA           mA           V           kV           °C/W	Minimum of the two values Norm: MIL 883 E method 3015 Typical FR4, 4-layer application The reflow peak soldering temperature (body temperature) specified is in compliance with <i>IPC/ JEDEC J-STD-020 "Moisture/ Reflow Sensitivity Classification for Non-Hermetic Solid State</i>
Continuous Output Current         Peak Output Current         Output Voltage         Electrostatic Discharge         Electrostatic Discharge HBM         Thermal Information         Thermal Resistance $\Theta$ JA         Gemperature Ranges and Storage Condition         Storage Temperature Range         Package Body Temperature         Humidity non-condensing	ons -40	PD/ (VIN - VOUT) 500 VIN + 0.3V or +7V +/- 1 	mA           mA           V           kV           °C/W	Norm: MIL 883 E method 3015 Typical FR4, 4-layer application
Peak Output Current         Output Voltage         Electrostatic Discharge         Electrostatic Discharge HBM         Thermal Information         Thermal Resistance $\Theta$ JA         Temperature Ranges and Storage Condition         Storage Temperature Range         Package Body Temperature         Humidity non-condensing	ons -40	(VIN - VOUT) 500 VIN + 0.3V or +7V +/- 1 230 +125	mA           V           kV           °C/W	Norm: MIL 883 E method 3015 Typical FR4, 4-layer application
Output Voltage         Electrostatic Discharge         Electrostatic Discharge HBM         Thermal Information         Thermal Resistance $\Theta$ JA         Temperature Ranges and Storage Condition         Storage Temperature Range         Package Body Temperature         Humidity non-condensing	ons -40	VIN + 0.3V or +7V +/- 1 230 +125	V kV °C/W	Norm: MIL 883 E method 3015 Typical FR4, 4-layer application
Electrostatic Discharge Electrostatic Discharge HBM Thermal Information Thermal Resistance $\Theta$ JA Temperature Ranges and Storage Condition Storage Temperature Range Package Body Temperature Humidity non-condensing	ons -40	or +7V +/- 1 230 +125	kV °C/W	Norm: MIL 883 E method 3015 Typical FR4, 4-layer application
Electrostatic Discharge HBM Thermal Information Thermal Resistance $\Theta$ JA Temperature Ranges and Storage Condition Storage Temperature Range Package Body Temperature Humidity non-condensing	ons -40	230	°C/W	Typical FR4, 4-layer application
Thermal Information         Thermal Resistance $\Theta$ JA         Temperature Ranges and Storage Condition         Storage Temperature Range         Package Body Temperature         Humidity non-condensing	ons -40	230	°C/W	Typical FR4, 4-layer application
Thermal Resistance $\Theta$ JA         cemperature Ranges and Storage Condition         Storage Temperature Range         Package Body Temperature         Humidity non-condensing	-40	+125	°C	
emperature Ranges and Storage Condition         Storage Temperature Range         Package Body Temperature         Humidity non-condensing	-40	+125	°C	
Storage Temperature Range Package Body Temperature Humidity non-condensing	-40			The reflow peak soldering temperature (body temperature) specified is in compliance with <i>IPC/JEDEC J-STD-020 "Moisture/ Reflow Sensitivity</i>
Package Body Temperature Humidity non-condensing				The reflow peak soldering temperature (body temperature) specified is in compliance with IPC/ JEDEC J-STD-020 "Moisture/ Reflow Sensitivity
Humidity non-condensing	5	+260	°C	The reflow peak soldering temperature (body temperature) specified is in compliance with <i>IPC/JEDEC J-STD-020 "Moisture/ Reflow Sensitivity</i>
	5			Classification for Non-Hermetic Solid State Surface Mount Devices".
Moisture Sensitive Level		85	%	
		1		Represents a max. floor life time of unlimited
	3			

# **6** Electrical Characteristics

Typical values are at TAMB =  $+25^{\circ}$ C, VDD = 3.3V (unless otherwise specified). All limits are guaranteed. The parameters with min and max values are guaranteed with production tests or SQC (Statistical Quality Control) methods.

Table 3. Electrical Characteristics
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Symbol	Parameter	Condition	Min	Тур	Max	Unit
Тамв	Operating Temperature Range		-40		+85	°C
Vin	Input Voltage				20	V
Vout	Output Voltage	lout = 40mA <sup>1</sup> , lout = 15mA if Vout = 1.8V	Voutnom - 1.5%	Voutnom ± 0.5%	Voutnom + 1.5%	V
		Vout = 5.0V (Vin = Voutnom + 1.0V)	250			
		Vout = 4.0V	200			
	M : 01 10 1	Vout = 3.3V	150			
IOUT(MAX)	Maximum Output Current	Vout = 3.0V	150			mA
		Vout = 2.5V	125			
		Vout = 2.1V	115			
		Vout = 1.8V	110			
ΔVουτ/Vout	Load Regulation <sup>2</sup>	Vout = 5.0V, $1\text{mA} \le 100\text{mA}$	-1.60	±0.8	+1.60	%
		Vout = 4.0V, $1mA \le Iout \le 100mA$	-2.25	±1.1	+2.25	
		Vout = 3.3V, 1mA ≤ Iout ≤ 80mA	-2.72	±1.3	+2.72	
		Vout = 3.0V, 1mA ≤ Iout ≤ 80mA	-3.00	±1.5	+3.00	
		Vout = 2.5V, 1mA ≤ Iout ≤ 60mA	-3.60	±1.8	+3.60	
		Vout = 2.1V, 1mA ≤ Iout ≤ 40mA	-2.60	±1.6	+2.60	
		Vout = 1.8V, 1mA ≤ Iout ≤ 30mA	-1.60	±0.8	+1.60	
$\Delta VOUT x 100/$ $\Delta VIN x VOUT$	Line Regulation	IOUT = 40mA, (VOUTNOM +1.0) ≤ VIN ≤ 10.0V		0.1	0.25	%/V
Vin - Vout		IOUT = 200mA, VOUTNOM = 5.0V		400	630	
	Dropout Voltage	IOUT = 200mA, VOUTNOM = 4.0V		400	700	
		IOUT = 160mA, VOUTNOM = 3.3V		400	700	
		IOUT = 160mA, VOUTNOM = 3.0V		400	700	mV
		IOUT = 120mA, VOUTNOM = 2.5V		400	700	-
		IOUT = 60mA, VOUTNOM = 2.1V		200	500	
		IOUT = 20mA, VOUTNOM = 1.8V		180	300	
lq	Input Quiescent Current	VIN = VOUTNOM +1.0V		1.5	3.0	μA
TCVout	Temperature Coefficient of VOUT <sup>3</sup>	lout = 40mA, -40°С ≤ Тамв ≤ +85°С		±100		ppm/ºC
tR	Output Rise Time	10% VOUTNOM to 90% VOUTNOM, VIN = 0V to VOUTNOM + 1V, RLOAD = $25\Omega$ resistive		150		μs

1. VOUTNOM is the nominal device output voltage.

2. Measured at a constant junction temperature using low duty cycle pulse testing.

3. TCVOUT = (VOH - VOL) x 10<sup>6</sup>/(VOUTNOM x Temperature). Where:

VOH is the highest voltage measured over the device temperature range. VOL is the lowest voltage over the device temperature range.

# 7 Typical Operating Characteristics

VOUT = 3.3V,  $ILOAD = 100\mu A$ , VIN = 4.3V,  $CIN 1\mu F$  (tantalum),  $COUT = 1\mu F$  (tantalum),  $TAMB = +25^{\circ}C$  (unless otherwise specified).

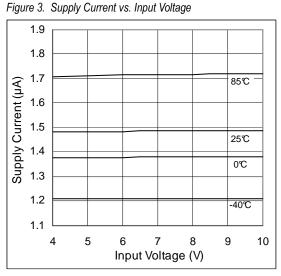
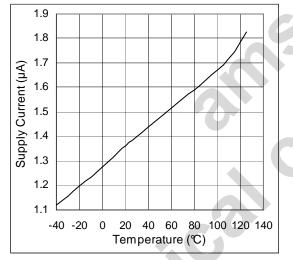
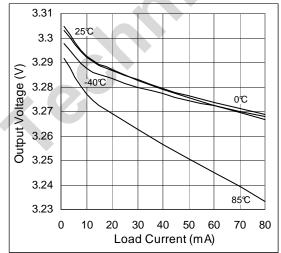


Figure 5. Supply Current vs. Temperature







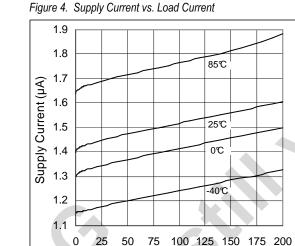
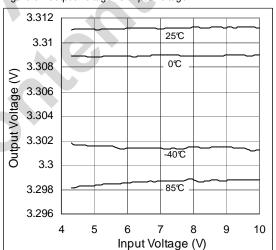
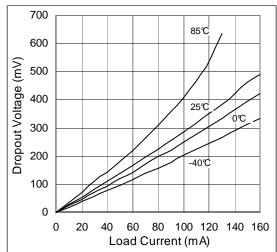


Figure 6. Output Voltage vs. Input Voltage



Load Current (mA)

Figure 8. Dropout Voltage vs. Load Current



#### Figure 9. Load Regulation vs. Temperature

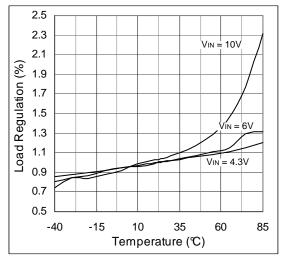


Figure 11. Output Voltage vs. Input Voltage; Dropout

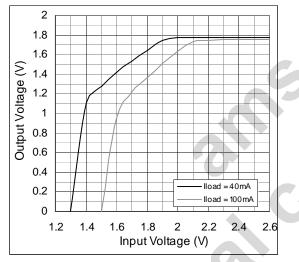


Figure 10. Line Regulation vs. Temperature

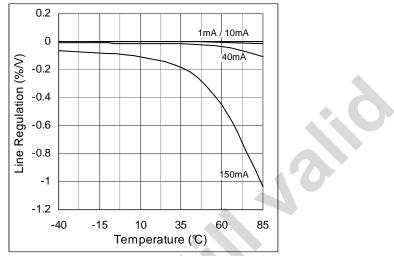


Figure 12. Startup Rise Time

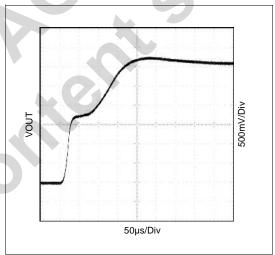
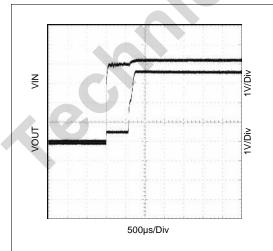


Figure 13. Startup Delay



**Note:** All graphs where measured without additional heat sinks, with the SOT23 package mounted on a 4-layer PCB. Adding additional heat sinks will improve performance in high temperature enviroment.

### 8 Detailed Description

The AS1360 is a low-power, positive voltage regulator designed in such a way that the supply current is independent from the load current. The device regulates the output by comparing the output voltage to an internally generated reference voltage.

The device is available in fixed output voltages of 1.8, 2.5, 3.0, 3.3, and 5.0V. Fixed output voltages are generated using the internal resistor divider network (see Figure 1 on page 1).

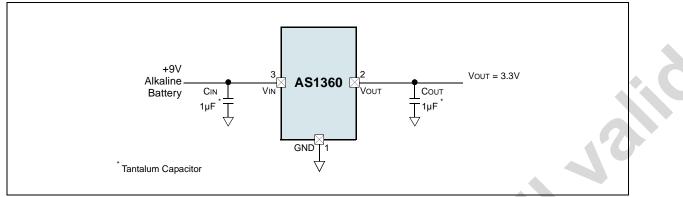
#### **Short Circuit/Overcurrent Protection**

The AS1360 monitors current flow through the p-channel MOSFET. In short-circuit or overcurrent conditions, the integrated short-circuit protection circuitry will limit output current.

Note: Thermal Dissipation according to Absolute Maximum Ratings on page 3 must be considered.

# 9 Application Information

Figure 14. AS1360 - Typical Application Diagram



#### **Power Dissipation**

Power dissipation (PD) of the AS1360 is the sum of the power dissipated by the p-channel MOSFET and the quiescent current required to bias the internal voltage reference and the internal power amplifier, and is calculated as:

Internal power dissipation as a result of the bias current for the internal voltage reference and the error amplifier is calculated as:

$$PD$$
 (Bias) = VINIGND (EQ 2)

Total AS1360 power dissipation is calculated as:

The internal quiescent bias current (2µA, typ) is such that the PD(Bias) term of (EQ 3) can be disregarded and the maximum power dissipation can be estimated using VIN(MAX) and VOUT(MIN) to obtain a maximum voltage differential between VIN and VOUT, and multiplying the maximum voltage differential by the maximum output current:

$$PD = (VIN(MAX)VOUT(MIN))IOUT(MAX)$$
(EQ 4)

#### Where:

VIN = 3.3 to 4.1V VOUT = 3.0V ±2% IOUT = 1 to 100mA TAMB(MAX) = 55°C PMAX = (4.1V - (3.0V x 0.98)) x 100mA = 116.0mW

#### **Junction Temperature**

The AS1360 junction temperature (TJ) can be determined by first calculating the thermal resistance from junction temperature-to-ambient temperature.

Note: Thermal resistance is estimated to be the junction temperature-to-air temperature RΦJA, and is approximately 230°C/W or 335°C/W (when mounted on 1 square inch of copper). RΦJA will vary depending on PCB layout, air-flow and application specific conditions.

The AS1360 junction temperature is determined by calculating the rise in TJ above TAMB, and then adding the increase of TAMB:

$$T_J = P_{D(MAX)} \times R_{\Phi JA} + T_{AMB} \tag{EQ 5}$$

From (EQ 5), the value of TJ can be calculated as:

TJ = 116.0mW x 230°C/W + 55°C

Therefore:

TJ = 81.68°C

### **External Component Selection**

#### Input Capacitor

In applications where input impedance is approximately 10Ω, a 1µF capacitor is sufficient for CIN (see Figure 14 on page 8).

In cases where the AS1360 is operated from a battery, or when there is significant distance between the input source to the AS1360, larger values for CIN may be required for output stability.

Note: For values of COUT > 1µF, the value of CIN should be increased to prevent high source-impedance oscillations.

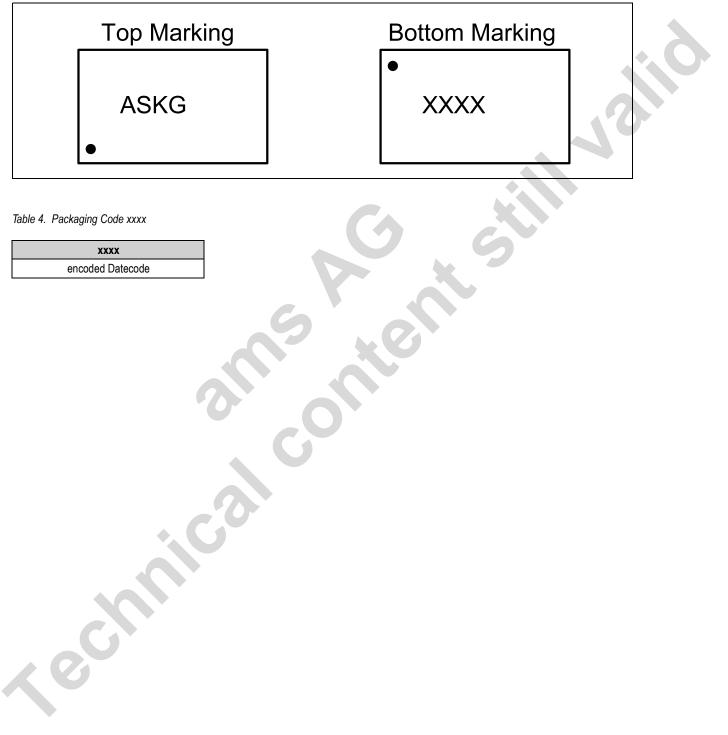
#### **Output Capacitor**

In most applications for the AS1360, a 1 $\mu$ F capacitor (ESR > 0.1 $\Omega$ /< 5 $\Omega$ , fRES > 1MHz) is sufficient for COUT (see Figure 14 on page 8). For improved power supply noise rejection and device transient response, larger values can be used for COUT.

Note: For values of COUT >  $1\mu$ F, the input impedance must not be so large that it causes high-input impedance oscillations.

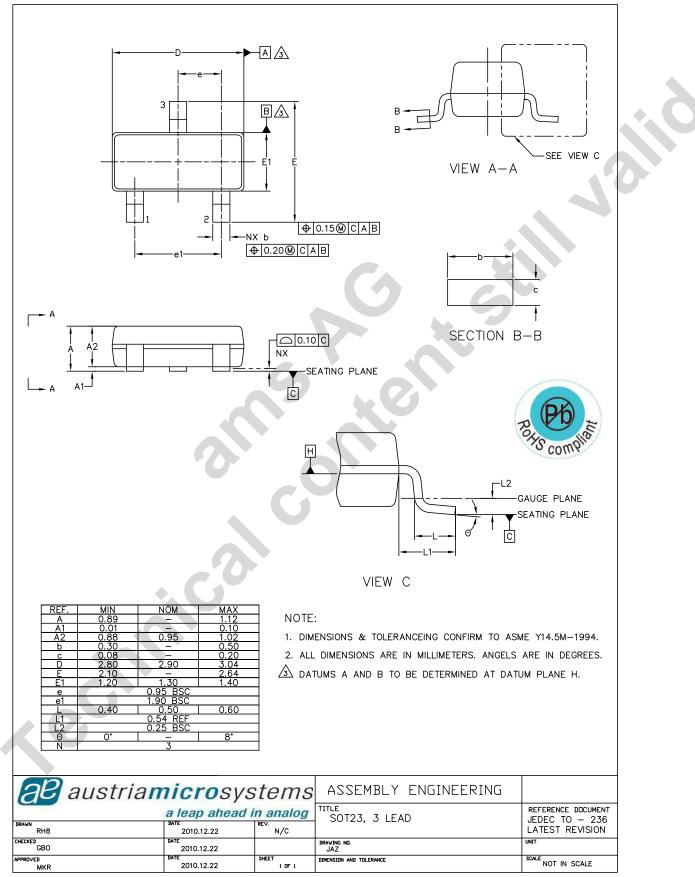
### **10 Package Drawings and Markings**

#### Figure 15. 3-pin SOT23 Marking



Datasheet - Package Drawings and Markings

#### Figure 16. 3-pin SOT23 Package



# **11 Ordering Information**

The device is available as the standard products shown in Table 5.

Table 5. Ordering Information

Ordering Code	Marking	Description	Delivery Form	Package
AS1360-18-T	ASKD	HV low-quiescent current LDO, 1.8V	Tape and Reel	3-pin SOT23
AS1360-21-T	ASRO	HV low-quiescent current LDO, 2.1V	Tape and Reel	3-pin SOT23
AS1360-25-T	ASKE	HV low-quiescent current LDO, 2.5V	Tape and Reel	3-pin SOT23
AS1360-30-T	ASKF	HV low-quiescent current LDO, 3.0V	Tape and Reel	3-pin SOT23
AS1360-33-T	ASKG	HV low-quiescent current LDO, 3.3V	Tape and Reel	3-pin SOT23
AS1360-40-T	ASQV	HV low-quiescent current LDO, 4.0V	Tape and Reel	3-pin SOT23
AS1360-45-T	ASTQ	HV low-quiescent current LDO, 4.5V	Tape and Reel	3-pin SOT23
AS1360-50-T	ASKH	HV low-quiescent current LDO, 5.0V	Tape and Reel	3-pin SOT23

**Note:** All products are RoHS compliant.

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